

# SOT1049-2

plastic extremely thin quad flat pack package; no leads; 10 terminals; UTLP based

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	XQFN10U
<b>Package type industry code</b>	XQFN10U
<b>Package style descriptive code</b>	XQFN (extremely thin quad flatpack; no leads)
<b>Package style suffix code</b>	U (UTLP based)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	- - -
<b>JEDEC package outline code</b>	MO-255
<b>JEITA package outline code</b>	- - -
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	5-2-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.45	-	1.55	1.65	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	[tbd]	-	[tbd]	0.5	mm
e	nominal pitch	-	-	0.58	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	10	-	

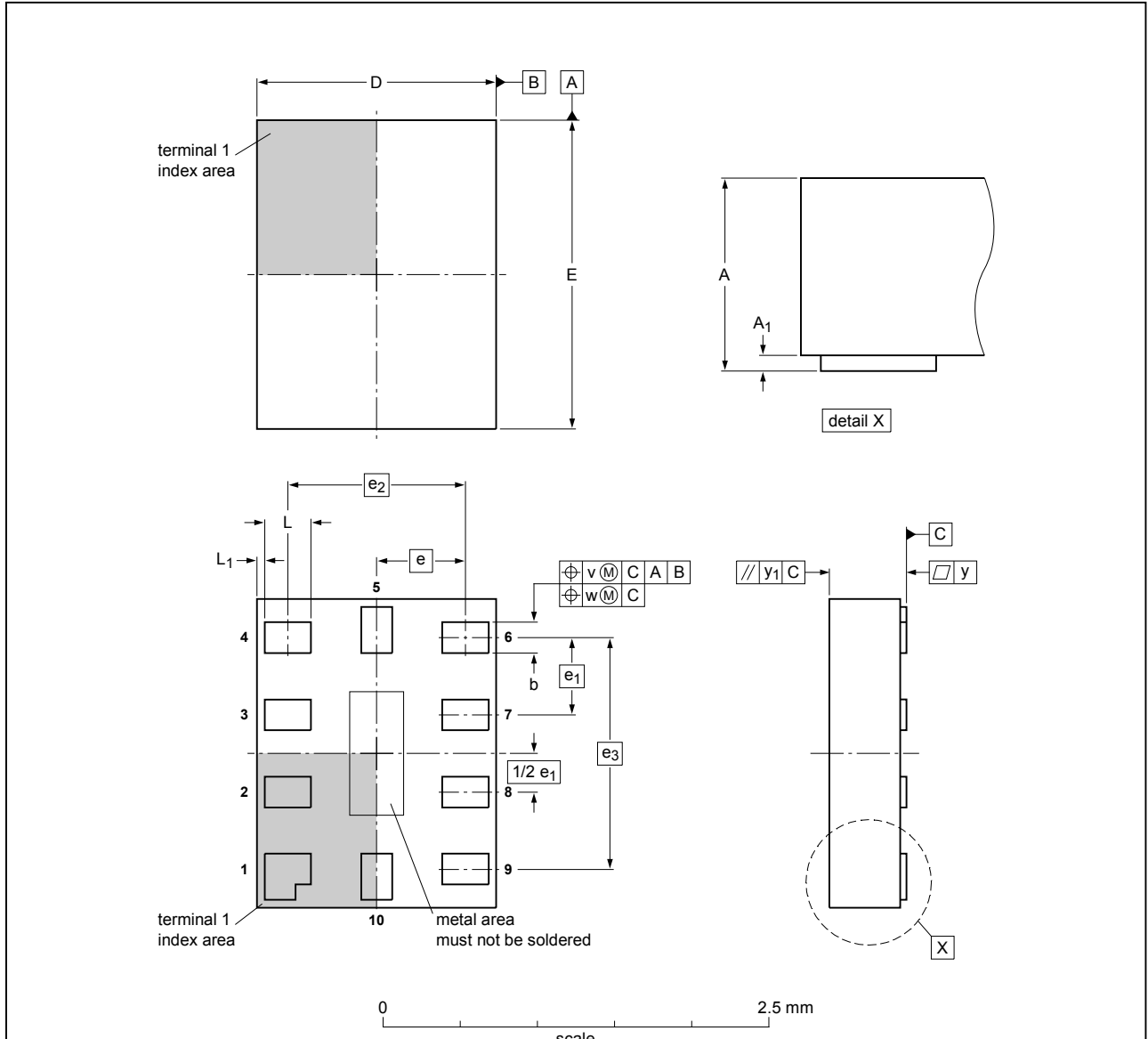


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## 2. Package outline

XQFN10U: plastic extremely thin quad flat pack package; no leads; 10 terminals; UTLP based; body 2 x 1.55 x 0.5 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	e <sub>2</sub>	e <sub>3</sub>	L	L <sub>1</sub>	v	w	y	y <sub>1</sub>	
mm	max	0.50	0.05	0.30	1.65	2.1	0.58	0.5	1.16	1.5	0.4	0.15	0.3	0.08	0.1	0.05
	nom		0.03	0.23	1.55	2.0					0.3	0.08	0.05	0.1	0.05	
	min		0.00	0.15	1.45	1.9					0.2	0.00				

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1049-2	---	MO-255	---			08-04-22 10-02-05

Fig. 1. Package outline XQFN10U (SOT1049-2)

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### 3. Legal information

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)  
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